SURFBOARDS R

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TM



ACCEPTS 33310 MODFI 10 LEAD .5 mm PITCH DEVICES **DEVICE LEAD WIDTH 1.5 To Max 2.5 MM** A 33310 В РIJЯ ЪЯ RЛ RЛ RЛ RЛ **₽**.А RЛ RЛ RЛ Ś P С Ŵ SINGLE-IN-LINE (SIP) PINS NOT TO SCALE ON .100 in. CENTERS EXAMPLE DEVICE (J PAD SET AND MAX WIDTH (I) 4 SIDED LEAD D FORMAT. 1

D1 ⊐-G

MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.



TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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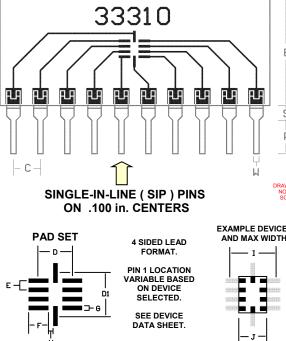
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PARTIAL LISTING

FAIRCHILD 10LD, MICROPAK 1.6MM

TEXAS INST. RSE (S-PQFP-N10) RUG (S-PQFP-N10)



ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

	JUST ADD PARTS AND PLUG-IN ™			
	FIG.	мм	IN.	NOTE:
s J)	Α	25.4	1.0	BOARD WIDTH +5mm .020in.
	в	10.16	.400	BOARD HEIGHT +5mm .020in.
	С	2.54	.100	SIP PIN SPACE +20mm .008in.
í	D	1.85	.073	PAD CENTERLINE
	D1	2.35	.093	PAD CENTERLINE OTHER AXIS
	Е	.5	.020	DEVICE LEAD PITCH
	F	1.1	.043	PAD LENGTH
	G	.25	.010	PAD WIDTH
	н	.25	.010	GAP
	Ι	2.5	.098	MAX LEAD WIDTH
	ſ	1.5	.059	TYPICAL LEAD WIDTH
	Ρ	3.3	.130	LENGTH FROM SHOULDER +- .5mm .020in.
,	S	1.57	.062	PIN SHOULDER HEGHT
	w	.5	.020	PIN WIDTH

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